



#### NOTES:

This PCB to be manufactured to meet all acceptance levels of a class 2 PCB per ANSI/IPC-A-600F.

MATERIAL: FR-4

THICKNESS: 0.062" +/- 0.005"

PLATING: 1 oz. Copper

LAYER COUNT: 2

CONTROLLED IMPEDENCE: No

Hot air solder leveled (HASL) exposed areas with 63/37 tin/lead solder.

Soldermask over bare copper (SMOBC)

SOLDERMASK TYPE: DYNACHEM EPIC 200 LPI or equivalent.

SOLDERMASK COLOR: Green

SILKSCREEN COLOR: White

All holes to be located by the coordinates from the NC drill data provided.

Use artwork set No. 05-01725 Rev. 1

Any alternatives to the above specifications must be approved by Microchip Technology Inc.

All dimensions are in inches.

DRILL TABLE				
Hole Dia (inch)	Symbol	Quantity	Plated	Tolerance
0.020	□	39	Yes	+/-0.003
0.035	+	6	Yes	+/-0.003
0.038	X	22	Yes	+/-0.003
0.042	Y	3	Yes	+/-0.003

#### Fabrication Drawing

Co:	Microchip Technology Inc.			
Title:	rFPIC Dev Kit 1 Xmtr Module			
Number:	04-01725	Revision:	1	
Author:	Steven Bible	Size:	A	
Date:	April 16, 2003	Sheet	1 of 1	